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Understanding **Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	2880
Number of Logic Elements/Cells	-
Total RAM Bits	-
Number of I/O	174
Number of Gates	48000
Voltage - Supply	2.25V ~ 5.25V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/a54sx32a-2pq208i

Where:

C_{EQCM} = Equivalent capacitance of combinatorial modules (C-cells) in pF

C_{EQSM} = Equivalent capacitance of sequential modules (R-Cells) in pF

C_{EQI} = Equivalent capacitance of input buffers in pF

C_{EQO} = Equivalent capacitance of output buffers in pF

C_{EQCR} = Equivalent capacitance of CLKA/B in pF

C_{EQHV} = Variable capacitance of HCLK in pF

C_{EQHF} = Fixed capacitance of HCLK in pF

C_L = Output lead capacitance in pF

f_m = Average logic module switching rate in MHz

f_n = Average input buffer switching rate in MHz

f_p = Average output buffer switching rate in MHz

f_{q1} = Average CLKA rate in MHz

f_{q2} = Average CLKB rate in MHz

f_{s1} = Average HCLK rate in MHz

m = Number of logic modules switching at f_m

n = Number of input buffers switching at f_n

p = Number of output buffers switching at f_p

q_1 = Number of clock loads on CLKA

q_2 = Number of clock loads on CLKB

r_1 = Fixed capacitance due to CLKA

r_2 = Fixed capacitance due to CLKB

s_1 = Number of clock loads on HCLK

x = Number of I/Os at logic low

y = Number of I/Os at logic high

Table 2-11 • CEQ Values for SX-A Devices

	A54SX08A	A54SX16A	A54SX32A	A54SX72A
Combinatorial modules (C_{EQCM})	1.70 pF	2.00 pF	2.00 pF	1.80 pF
Sequential modules (C_{EQCM})	1.50 pF	1.50 pF	1.30 pF	1.50 pF
Input buffers (C_{EQI})	1.30 pF	1.30 pF	1.30 pF	1.30 pF
Output buffers (C_{EQO})	7.40 pF	7.40 pF	7.40 pF	7.40 pF
Routed array clocks (C_{EQCR})	1.05 pF	1.05 pF	1.05 pF	1.05 pF
Dedicated array clocks – variable (C_{EQHV})	0.85 pF	0.85 pF	0.85 pF	0.85 pF
Dedicated array clocks – fixed (C_{EQHF})	30.00 pF	55.00 pF	110.00 pF	240.00 pF
Routed array clock A (r_1)	35.00 pF	50.00 pF	90.00 pF	310.00 pF

Thermal Characteristics

Introduction

The temperature variable in Actel Designer software refers to the junction temperature, not the ambient, case, or board temperatures. This is an important distinction because dynamic and static power consumption will cause the chip's junction to be higher than the ambient, case, or board temperatures. EQ 2-9 and EQ 2-10 give the relationship between thermal resistance, temperature gradient and power.

$$\theta_{JA} = \frac{T_J - T_A}{P}$$

EQ 2-9

$$\theta_{JC} = \frac{T_C - T_A}{P}$$

EQ 2-10

Where:

θ_{JA} = Junction-to-air thermal resistance

θ_{JC} = Junction-to-case thermal resistance

T_J = Junction temperature

T_A = Ambient temperature

T_C = Case temperature

P = total power dissipated by the device

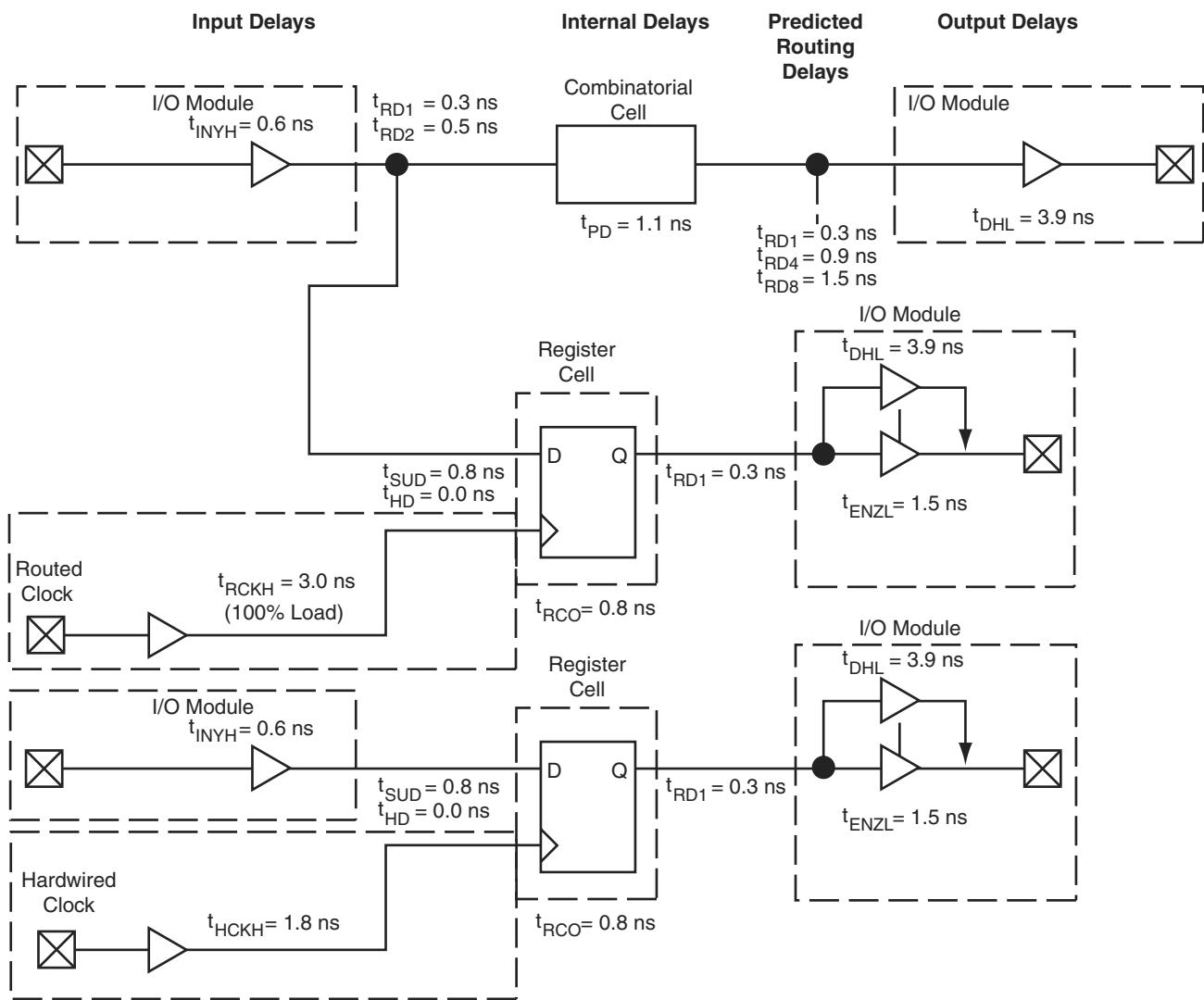
Table 2-12 • Package Thermal Characteristics

Package Type	Pin Count	θ_{JC}	θ_{JA}			Units
			Still Air	1.0 m/s 200 ft./min.	2.5 m/s 500 ft./min.	
Thin Quad Flat Pack (TQFP)	100	14	33.5	27.4	25	°C/W
Thin Quad Flat Pack (TQFP)	144	11	33.5	28	25.7	°C/W
Thin Quad Flat Pack (TQFP)	176	11	24.7	19.9	18	°C/W
Plastic Quad Flat Pack (PQFP) ¹	208	8	26.1	22.5	20.8	°C/W
Plastic Quad Flat Pack (PQFP) with Heat Spreader ²	208	3.8	16.2	13.3	11.9	°C/W
Plastic Ball Grid Array (PBGA)	329	3	17.1	13.8	12.8	°C/W
Fine Pitch Ball Grid Array (FBGA)	144	3.8	26.9	22.9	21.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.8	26.6	22.8	21.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	484	3.2	18	14.7	13.6	°C/W

Notes:

1. The A54SX08A PQ208 has no heat spreader.
2. The SX-A PQ208 package has a heat spreader for A54SX16A, A54SX32A, and A54SX72A.

SX-A Timing Model



Note: *Values shown for A54SX72A, -2, worst-case commercial conditions at 5 V PCI with standard place-and-route.

Figure 2-3 • SX-A Timing Model

Sample Path Calculations

Hardwired Clock

$$\begin{aligned}
 \text{External Setup} &= (t_{INYH} + t_{RD1} + t_{SUD}) - t_{HCKH} \\
 &= 0.6 + 0.3 + 0.8 - 1.8 = -0.1 \text{ ns} \\
 \text{Clock-to-Out (Pad-to-Pad)} &= t_{HCKH} + t_{RCO} + t_{RD1} + t_{DHL} \\
 &= 1.8 + 0.8 + 0.3 + 3.9 = 6.8 \text{ ns}
 \end{aligned}$$

Routed Clock

$$\begin{aligned}
 \text{External Setup} &= (t_{INYH} + t_{RD1} + t_{SUD}) - t_{RCKH} \\
 &= 0.6 + 0.3 + 0.8 - 3.0 = -1.3 \text{ ns} \\
 \text{Clock-to-Out (Pad-to-Pad)} &= t_{RCKH} + t_{RCO} + t_{RD1} + t_{DHL} \\
 &= 3.0 + 0.8 + 0.3 + 3.9 = 8.0 \text{ ns}
 \end{aligned}$$

Timing Characteristics

Table 2-14 • A54SX08A Timing Characteristics
(Worst-Case Commercial Conditions, $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-2 Speed		-1 Speed		Std. Speed		-F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
C-Cell Propagation Delays¹										
t_{PD}	Internal Array Module	0.9	1.1	1.2	1.7	ns				
Predicted Routing Delays²										
t_{RD1}	FO = 1 Routing Delay, Direct Connect	0.1	0.1	0.1	0.1	0.1	0.1	0.1	0.1	ns
t_{RD2}	FO = 1 Routing Delay, Fast Connect	0.3	0.3	0.4	0.4	0.5	0.5	0.6	0.6	ns
t_{RD3}	FO = 1 Routing Delay	0.3	0.4	0.5	0.6	0.6	0.7	0.8	0.9	ns
t_{RD4}	FO = 2 Routing Delay	0.5	0.5	0.6	0.6	0.7	0.7	0.8	0.8	ns
t_{RD8}	FO = 3 Routing Delay	0.6	0.7	0.8	0.8	0.9	0.9	1.1	1.1	ns
t_{RD12}	FO = 4 Routing Delay	0.8	0.9	1	1	1.1	1.2	1.4	1.4	ns
t_{RD16}	FO = 8 Routing Delay	1.4	1.5	1.8	1.8	2.0	2.0	2.5	2.5	ns
t_{RD32}	FO = 12 Routing Delay	2	2.2	2.6	2.6	2.8	2.8	3.6	3.6	ns
R-Cell Timing										
t_{RCO}	Sequential Clock-to-Q	0.7	0.8	0.9	0.9	1.0	1.0	1.3	1.3	ns
t_{CLR}	Asynchronous Clear-to-Q	0.6	0.6	0.8	0.8	1.0	1.0	1.0	1.0	ns
t_{PRESET}	Asynchronous Preset-to-Q	0.7	0.7	0.9	0.9	1.2	1.2	1.2	1.2	ns
t_{SUD}	Flip-Flop Data Input Set-Up	0.7	0.8	0.9	0.9	1.2	1.2	1.2	1.2	ns
t_{HD}	Flip-Flop Data Input Hold	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	ns
t_{WASYN}	Asynchronous Pulse Width	1.4	1.5	1.8	1.8	2.5	2.5	2.5	2.5	ns
$t_{RECASYN}$	Asynchronous Recovery Time	0.4	0.4	0.5	0.5	0.7	0.7	0.7	0.7	ns
t_{HASYN}	Asynchronous Hold Time	0.3	0.3	0.4	0.4	0.6	0.6	0.6	0.6	ns
t_{MPW}	Clock Pulse Width	1.6	1.8	2.1	2.1	2.9	2.9	2.9	2.9	ns
Input Module Propagation Delays										
t_{INYH}	Input Data Pad to Y High 2.5 V LVC MOS	0.8	0.9	1.0	1.0	1.4	1.4	1.4	1.4	ns
t_{INYL}	Input Data Pad to Y Low 2.5 V LVC MOS	1.0	1.2	1.4	1.4	1.9	1.9	1.9	1.9	ns
t_{INYH}	Input Data Pad to Y High 3.3 V PCI	0.6	0.6	0.7	0.7	1.0	1.0	1.0	1.0	ns
t_{INYL}	Input Data Pad to Y Low 3.3 V PCI	0.7	0.8	0.9	0.9	1.3	1.3	1.3	1.3	ns
t_{INYH}	Input Data Pad to Y High 3.3 V LVTTL	0.7	0.7	0.9	0.9	1.2	1.2	1.2	1.2	ns
t_{INYL}	Input Data Pad to Y Low 3.3 V LVTTL	1.0	1.1	1.3	1.3	1.8	1.8	1.8	1.8	ns

Notes:

- For dual-module macros, use $t_{PD} + t_{RD1} + t_{PDn}$, $t_{RCO} + t_{RD1} + t_{PDn}$, or $t_{PD1} + t_{RD1} + t_{SUD}$, whichever is appropriate.
- Routing delays are for typical designs across worst-case operating conditions. These parameters should be used for estimating device performance. Post-route timing analysis or simulation is required to determine actual performance.

Table 2-22 • A54SX16A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 2.25\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed*	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
Dedicated (Hardwired) Array Clock Networks							
t_{HCKH}	Input Low to High (Pad to R-cell Input)	1.2	1.4	1.6	1.8	2.8	ns
t_{HCKL}	Input High to Low (Pad to R-cell Input)	1.0	1.1	1.2	1.5	2.2	ns
t_{HPWH}	Minimum Pulse Width High	1.4	1.7	1.9	2.2	3.0	ns
t_{HPWL}	Minimum Pulse Width Low	1.4	1.7	1.9	2.2	3.0	ns
t_{HCKSW}	Maximum Skew	0.3	0.3	0.4	0.4	0.7	ns
t_{HP}	Minimum Period	2.8	3.4	3.8	4.4	6.0	ns
f_{HMAX}	Maximum Frequency	357	294	263	227	167	MHz
Routed Array Clock Networks							
t_{RCKH}	Input Low to High (Light Load) (Pad to R-cell Input)	1.0	1.2	1.3	1.6	2.2	ns
t_{RCKL}	Input High to Low (Light Load) (Pad to R-cell Input)	1.1	1.3	1.5	1.7	2.4	ns
t_{RCKH}	Input Low to High (50% Load) (Pad to R-cell Input)	1.1	1.3	1.5	1.7	2.4	ns
t_{RCKL}	Input High to Low (50% Load) (Pad to R-cell Input)	1.1	1.3	1.5	1.7	2.4	ns
t_{RCKH}	Input Low to High (100% Load) (Pad to R-cell Input)	1.3	1.5	1.7	2.0	2.8	ns
t_{RCKL}	Input High to Low (100% Load) (Pad to R-cell Input)	1.3	1.5	1.7	2.0	2.8	ns
t_{RPWH}	Minimum Pulse Width High	1.4	1.7	1.9	2.2	3.0	ns
t_{RPWL}	Minimum Pulse Width Low	1.4	1.7	1.9	2.2	3.0	ns
t_{RCKSW}	Maximum Skew (Light Load)	0.8	0.9	1.0	1.2	1.7	ns
t_{RCKSW}	Maximum Skew (50% Load)	0.8	0.9	1.0	1.2	1.7	ns
t_{RCKSW}	Maximum Skew (100% Load)	1.0	1.1	1.3	1.5	2.1	ns

Note: *All -3 speed grades have been discontinued.

Table 2-24 • A54SX16A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 4.75\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed*	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
Dedicated (Hardwired) Array Clock Networks							
t_{HCKH}	Input Low to High (Pad to R-cell Input)	1.2	1.4	1.6	1.8	2.8	ns
t_{HCKL}	Input High to Low (Pad to R-cell Input)	1.0	1.1	1.2	1.5	2.2	ns
t_{HPWH}	Minimum Pulse Width High	1.4	1.7	1.9	2.2	3.0	ns
t_{HPWL}	Minimum Pulse Width Low	1.4	1.7	1.9	2.2	3.0	ns
t_{HCKSW}	Maximum Skew	0.3	0.3	0.4	0.4	0.7	ns
t_{HP}	Minimum Period	2.8	3.4	3.8	4.4	6.0	ns
f_{HMAX}	Maximum Frequency	357	294	263	227	167	MHz
Routed Array Clock Networks							
t_{RCKH}	Input Low to High (Light Load) (Pad to R-cell Input)	1.0	1.2	1.3	1.6	2.2	ns
t_{RCKL}	Input High to Low (Light Load) (Pad to R-cell Input)	1.1	1.3	1.5	1.7	2.4	ns
t_{RCKH}	Input Low to High (50% Load) (Pad to R-cell Input)	1.1	1.3	1.5	1.7	2.4	ns
t_{RCKL}	Input High to Low (50% Load) (Pad to R-cell Input)	1.1	1.3	1.5	1.7	2.4	ns
t_{RCKH}	Input Low to High (100% Load) (Pad to R-cell Input)	1.3	1.5	1.7	2.0	2.8	ns
t_{RCKL}	Input High to Low (100% Load) (Pad to R-cell Input)	1.3	1.5	1.7	2.0	2.8	ns
t_{RPWH}	Minimum Pulse Width High	1.4	1.7	1.9	2.2	3.0	ns
t_{RPWL}	Minimum Pulse Width Low	1.4	1.7	1.9	2.2	3.0	ns
t_{RCKSW}	Maximum Skew (Light Load)	0.8	0.9	1.0	1.2	1.7	ns
t_{RCKSW}	Maximum Skew (50% Load)	0.8	0.9	1.0	1.2	1.7	ns
t_{RCKSW}	Maximum Skew (100% Load)	1.0	1.1	1.3	1.5	2.1	ns

Note: *All -3 speed grades have been discontinued.

Table 2-30 • A54SX32A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed*	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
Dedicated (Hardwired) Array Clock Networks							
t_{HCKH}	Input Low to High (Pad to R-cell Input)	1.7	2.0	2.2	2.6	4.0	ns
t_{HCKL}	Input High to Low (Pad to R-cell Input)	1.7	2.0	2.2	2.6	4.0	ns
t_{HPWH}	Minimum Pulse Width High	1.4	1.6	1.8	2.1	2.9	ns
t_{HPWL}	Minimum Pulse Width Low	1.4	1.6	1.8	2.1	2.9	ns
t_{HCKSW}	Maximum Skew	0.6	0.6	0.7	0.8	1.3	ns
t_{HP}	Minimum Period	2.8	3.2	3.6	4.2	5.8	ns
f_{HMAX}	Maximum Frequency	357	313	278	238	172	MHz
Routed Array Clock Networks							
t_{RCKH}	Input Low to High (Light Load) (Pad to R-cell Input)	2.2	2.5	2.8	3.3	4.6	ns
t_{RCKL}	Input High to Low (Light Load) (Pad to R-cell Input)	2.1	2.4	2.7	3.2	4.5	ns
t_{RCKH}	Input Low to High (50% Load) (Pad to R-cell Input)	2.3	2.7	3.1	3.6	5	ns
t_{RCKL}	Input High to Low (50% Load) (Pad to R-cell Input)	2.2	2.5	2.9	3.4	4.7	ns
t_{RCKH}	Input Low to High (100% Load) (Pad to R-cell Input)	2.4	2.8	3.2	3.7	5.2	ns
t_{RCKL}	Input High to Low (100% Load) (Pad to R-cell Input)	2.4	2.8	3.1	3.7	5.1	ns
t_{RPWH}	Minimum Pulse Width High	1.4	1.6	1.8	2.1	2.9	ns
t_{RPWL}	Minimum Pulse Width Low	1.4	1.6	1.8	2.1	2.9	ns
t_{RCKSW}	Maximum Skew (Light Load)	1.0	1.1	1.3	1.5	2.1	ns
t_{RCKSW}	Maximum Skew (50% Load)	0.9	1.0	1.2	1.4	1.9	ns
t_{RCKSW}	Maximum Skew (100% Load)	0.9	1.0	1.2	1.4	1.9	ns

Note: *All -3 speed grades have been discontinued.

Table 2-33 • A54SX32A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed¹	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
3.3 V PCI Output Module Timing²							
t_{DLH}	Data-to-Pad Low to High	1.9	2.2	2.4	2.9	4.0	ns
t_{DHL}	Data-to-Pad High to Low	2.0	2.3	2.6	3.1	4.3	ns
t_{ENZL}	Enable-to-Pad, Z to L	1.4	1.7	1.9	2.2	3.1	ns
t_{ENZH}	Enable-to-Pad, Z to H	1.9	2.2	2.4	2.9	4.0	ns
t_{ENLZ}	Enable-to-Pad, L to Z	2.5	2.8	3.2	3.8	5.3	ns
t_{ENHZ}	Enable-to-Pad, H to Z	2.0	2.3	2.6	3.1	4.3	ns
d_{TLH}^3	Delta Low to High	0.025	0.03	0.03	0.04	0.045	ns/pF
d_{THL}^3	Delta High to Low	0.015	0.015	0.015	0.015	0.025	ns/pF
3.3 V LVTTL Output Module Timing⁴							
t_{DLH}	Data-to-Pad Low to High	2.6	3.0	3.4	4.0	5.6	ns
t_{DHL}	Data-to-Pad High to Low	2.6	3.0	3.3	3.9	5.5	ns
t_{DHLS}	Data-to-Pad High to Low—low slew	9.0	10.4	11.8	13.8	19.3	ns
t_{ENZL}	Enable-to-Pad, Z to L	2.2	2.6	2.9	3.4	4.8	ns
t_{ENZLS}	Enable-to-Pad, Z to L—low slew	15.8	18.9	21.3	25.4	34.9	ns
t_{ENZH}	Enable-to-Pad, Z to H	2.6	3.0	3.4	4.0	5.6	ns
t_{ENLZ}	Enable-to-Pad, L to Z	2.9	3.3	3.7	4.4	6.2	ns
t_{ENHZ}	Enable-to-Pad, H to Z	2.6	3.0	3.3	3.9	5.5	ns
d_{TLH}^3	Delta Low to High	0.025	0.03	0.03	0.04	0.045	ns/pF
d_{THL}^3	Delta High to Low	0.015	0.015	0.015	0.015	0.025	ns/pF
d_{THLS}^3	Delta High to Low—low slew	0.053	0.053	0.067	0.073	0.107	ns/pF

Notes:

1. All -3 speed grades have been discontinued.
2. Delays based on 10 pF loading and 25 Ω resistance.
3. To obtain the slew rate, substitute the appropriate Delta value, load capacitance, and the V_{CCI} value into the following equation:

$$\text{Slew Rate [V/ns]} = (0.1 * V_{CCI} - 0.9 * V_{CCI}) / (C_{load} * d_{T[LH|HL|HLS]})$$

where C_{load} is the load capacitance driven by the I/O in pF.
 $d_{T[LH|HL|HLS]}$ is the worst case delta value from the datasheet in ns/pF.
4. Delays based on 35 pF loading.

Table 2-38 • A54SX72A Timing Characteristics (Continued)
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 4.75\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed*	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
t_{QCKH}	Input Low to High (100% Load) (Pad to R-cell Input)	1.6	1.8	2.1	2.4	3.4	ns
t_{QCHKL}	Input High to Low (100% Load) (Pad to R-cell Input)	1.6	1.9	2.1	2.5	3.5	ns
t_{QPWH}	Minimum Pulse Width High	1.5	1.7	2.0	2.3	3.2	ns
t_{QPWL}	Minimum Pulse Width Low	1.5	1.7	2.0	2.3	3.2	ns
t_{QCKSW}	Maximum Skew (Light Load)	0.2	0.3	0.3	0.3	0.5	ns
t_{QCKSW}	Maximum Skew (50% Load)	0.4	0.5	0.5	0.6	0.9	ns
t_{QCKSW}	Maximum Skew (100% Load)	0.4	0.5	0.5	0.6	0.9	ns

Note: *All -3 speed grades have been discontinued.

208-Pin PQFP				
Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function	A54SX72A Function
1	GND	GND	GND	GND
2	TDI, I/O	TDI, I/O	TDI, I/O	TDI, I/O
3	I/O	I/O	I/O	I/O
4	NC	I/O	I/O	I/O
5	I/O	I/O	I/O	I/O
6	NC	I/O	I/O	I/O
7	I/O	I/O	I/O	I/O
8	I/O	I/O	I/O	I/O
9	I/O	I/O	I/O	I/O
10	I/O	I/O	I/O	I/O
11	TMS	TMS	TMS	TMS
12	V _{CCI}	V _{CCI}	V _{CCI}	V _{CCI}
13	I/O	I/O	I/O	I/O
14	NC	I/O	I/O	I/O
15	I/O	I/O	I/O	I/O
16	I/O	I/O	I/O	I/O
17	NC	I/O	I/O	I/O
18	I/O	I/O	I/O	GND
19	I/O	I/O	I/O	V _{CCA}
20	NC	I/O	I/O	I/O
21	I/O	I/O	I/O	I/O
22	I/O	I/O	I/O	I/O
23	NC	I/O	I/O	I/O
24	I/O	I/O	I/O	I/O
25	NC	NC	NC	I/O
26	GND	GND	GND	GND
27	V _{CCA}	V _{CCA}	V _{CCA}	V _{CCA}
28	GND	GND	GND	GND
29	I/O	I/O	I/O	I/O
30	TRST, I/O	TRST, I/O	TRST, I/O	TRST, I/O
31	NC	I/O	I/O	I/O
32	I/O	I/O	I/O	I/O
33	I/O	I/O	I/O	I/O
34	I/O	I/O	I/O	I/O
35	NC	I/O	I/O	I/O

208-Pin PQFP				
Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function	A54SX72A Function
36	I/O	I/O	I/O	I/O
37	I/O	I/O	I/O	I/O
38	I/O	I/O	I/O	I/O
39	NC	I/O	I/O	I/O
40	V _{CCI}	V _{CCI}	V _{CCI}	V _{CCI}
41	V _{CCA}	V _{CCA}	V _{CCA}	V _{CCA}
42	I/O	I/O	I/O	I/O
43	I/O	I/O	I/O	I/O
44	I/O	I/O	I/O	I/O
45	I/O	I/O	I/O	I/O
46	I/O	I/O	I/O	I/O
47	I/O	I/O	I/O	I/O
48	NC	I/O	I/O	I/O
49	I/O	I/O	I/O	I/O
50	NC	I/O	I/O	I/O
51	I/O	I/O	I/O	I/O
52	GND	GND	GND	GND
53	I/O	I/O	I/O	I/O
54	I/O	I/O	I/O	I/O
55	I/O	I/O	I/O	I/O
56	I/O	I/O	I/O	I/O
57	I/O	I/O	I/O	I/O
58	I/O	I/O	I/O	I/O
59	I/O	I/O	I/O	I/O
60	V _{CCI}	V _{CCI}	V _{CCI}	V _{CCI}
61	NC	I/O	I/O	I/O
62	I/O	I/O	I/O	I/O
63	I/O	I/O	I/O	I/O
64	NC	I/O	I/O	I/O
65	I/O	I/O	NC	I/O
66	I/O	I/O	I/O	I/O
67	NC	I/O	I/O	I/O
68	I/O	I/O	I/O	I/O
69	I/O	I/O	I/O	I/O
70	NC	I/O	I/O	I/O

100-Pin TQFP

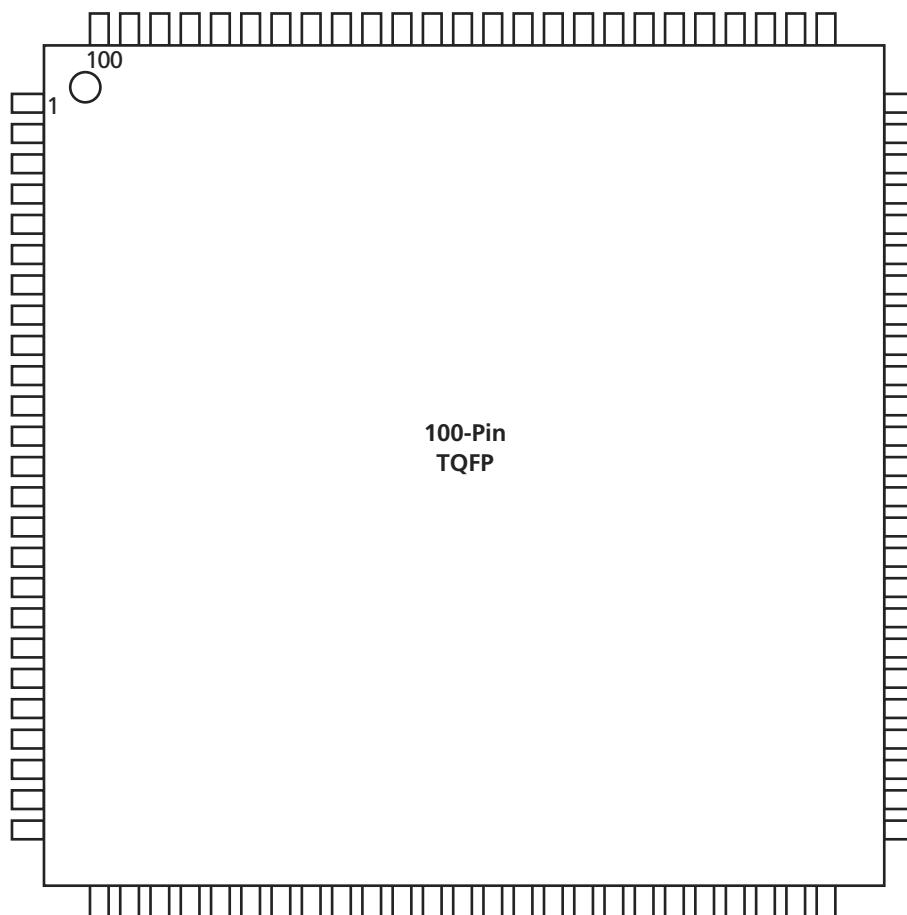


Figure 3-2 • 100-Pin TQFP

Note

For Package Manufacturing and Environmental information, visit Resource center at <http://www.actel.com/products/rescenter/package/index.html>.

144-Pin TQFP

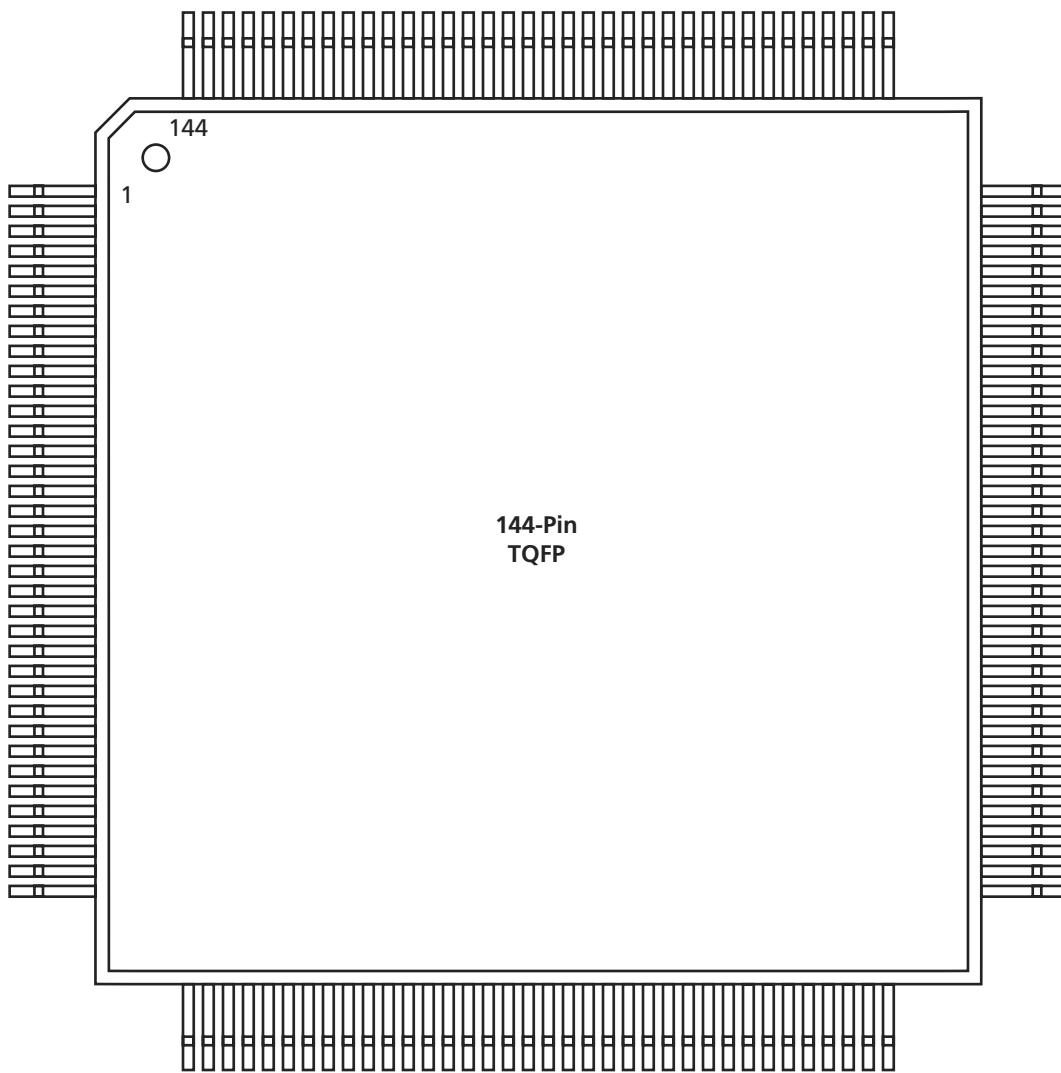


Figure 3-3 • 144-Pin TQFP (Top View)

Note

For Package Manufacturing and Environmental information, visit Resource center at
<http://www.actel.com/products/rescenter/package/index.html>.

144-Pin TQFP			
Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function
75	I/O	I/O	I/O
76	I/O	I/O	I/O
77	I/O	I/O	I/O
78	I/O	I/O	I/O
79	V _{CCA}	V _{CCA}	V _{CCA}
80	V _{CCI}	V _{CCI}	V _{CCI}
81	GND	GND	GND
82	I/O	I/O	I/O
83	I/O	I/O	I/O
84	I/O	I/O	I/O
85	I/O	I/O	I/O
86	I/O	I/O	I/O
87	I/O	I/O	I/O
88	I/O	I/O	I/O
89	V _{CCA}	V _{CCA}	V _{CCA}
90	NC	NC	NC
91	I/O	I/O	I/O
92	I/O	I/O	I/O
93	I/O	I/O	I/O
94	I/O	I/O	I/O
95	I/O	I/O	I/O
96	I/O	I/O	I/O
97	I/O	I/O	I/O
98	V _{CCA}	V _{CCA}	V _{CCA}
99	GND	GND	GND
100	I/O	I/O	I/O
101	GND	GND	GND
102	V _{CCI}	V _{CCI}	V _{CCI}
103	I/O	I/O	I/O
104	I/O	I/O	I/O
105	I/O	I/O	I/O
106	I/O	I/O	I/O
107	I/O	I/O	I/O
108	I/O	I/O	I/O
109	GND	GND	GND
110	I/O	I/O	I/O

144-Pin TQFP			
Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function
111	I/O	I/O	I/O
112	I/O	I/O	I/O
113	I/O	I/O	I/O
114	I/O	I/O	I/O
115	V _{CCI}	V _{CCI}	V _{CCI}
116	I/O	I/O	I/O
117	I/O	I/O	I/O
118	I/O	I/O	I/O
119	I/O	I/O	I/O
120	I/O	I/O	I/O
121	I/O	I/O	I/O
122	I/O	I/O	I/O
123	I/O	I/O	I/O
124	I/O	I/O	I/O
125	CLKA	CLKA	CLKA
126	CLKB	CLKB	CLKB
127	NC	NC	NC
128	GND	GND	GND
129	V _{CCA}	V _{CCA}	V _{CCA}
130	I/O	I/O	I/O
131	PRA, I/O	PRA, I/O	PRA, I/O
132	I/O	I/O	I/O
133	I/O	I/O	I/O
134	I/O	I/O	I/O
135	I/O	I/O	I/O
136	I/O	I/O	I/O
137	I/O	I/O	I/O
138	I/O	I/O	I/O
139	I/O	I/O	I/O
140	V _{CCI}	V _{CCI}	V _{CCI}
141	I/O	I/O	I/O
142	I/O	I/O	I/O
143	I/O	I/O	I/O
144	TCK, I/O	TCK, I/O	TCK, I/O

329-Pin PBGA	
Pin Number	A54SX32A Function
D11	V _{CCA}
D12	NC
D13	I/O
D14	I/O
D15	I/O
D16	I/O
D17	I/O
D18	I/O
D19	I/O
D20	I/O
D21	I/O
D22	I/O
D23	I/O
E1	V _{CCI}
E2	I/O
E3	I/O
E4	I/O
E20	I/O
E21	I/O
E22	I/O
E23	I/O
F1	I/O
F2	TMS
F3	I/O
F4	I/O
F20	I/O
F21	I/O
F22	I/O
F23	I/O
G1	I/O
G2	I/O
G3	I/O
G4	I/O
G20	I/O
G21	I/O
G22	I/O
G23	GND

329-Pin PBGA	
Pin Number	A54SX32A Function
H1	I/O
H2	I/O
H3	I/O
H4	I/O
H20	V _{CCA}
H21	I/O
H22	I/O
H23	I/O
J1	NC
J2	I/O
J3	I/O
J4	I/O
J20	I/O
J21	I/O
J22	I/O
J23	I/O
K1	I/O
K2	I/O
K3	I/O
K4	I/O
K10	GND
K11	GND
K12	GND
K13	GND
K14	GND
K20	I/O
K21	I/O
K22	I/O
K23	I/O
L1	I/O
L2	I/O
L3	I/O
L4	NC
L10	GND
L11	GND
L12	GND
L13	GND

329-Pin PBGA	
Pin Number	A54SX32A Function
L14	GND
L20	NC
L21	I/O
L22	I/O
L23	NC
M1	I/O
M2	I/O
M3	I/O
M4	V _{CCA}
M10	GND
M11	GND
M12	GND
M13	GND
M14	GND
M20	V _{CCA}
M21	I/O
M22	I/O
M23	V _{CCI}
N1	I/O
N2	TRST, I/O
N3	I/O
N4	I/O
N10	GND
N11	GND
N12	GND
N13	GND
N14	GND
N20	NC
N21	I/O
N22	I/O
N23	I/O
P1	I/O
P2	I/O
P3	I/O
P4	I/O
P10	GND
P11	GND

329-Pin PBGA	
Pin Number	A54SX32A Function
P12	GND
P13	GND
P14	GND
P20	I/O
P21	I/O
P22	I/O
P23	I/O
R1	I/O
R2	I/O
R3	I/O
R4	I/O
R20	I/O
R21	I/O
R22	I/O
R23	I/O
T1	I/O
T2	I/O
T3	I/O
T4	I/O
T20	I/O
T21	I/O
T22	I/O
T23	I/O
U1	I/O
U2	I/O
U3	V _{CCA}
U4	I/O
U20	I/O
U21	V _{CCA}
U22	I/O
U23	I/O
V1	V _{CCI}
V2	I/O
V3	I/O
V4	I/O
V20	I/O
V21	I/O

329-Pin PBGA	
Pin Number	A54SX32A Function
V22	I/O
V23	I/O
W1	I/O
W2	I/O
W3	I/O
W4	I/O
W20	I/O
W21	I/O
W22	I/O
W23	NC
Y1	NC
Y2	I/O
Y3	I/O
Y4	GND
Y5	I/O
Y6	I/O
Y7	I/O
Y8	I/O
Y9	I/O
Y10	I/O
Y11	I/O
Y12	V _{CCA}
Y13	NC
Y14	I/O
Y15	I/O
Y16	I/O
Y17	I/O
Y18	I/O
Y19	I/O
Y20	GND
Y21	I/O
Y22	I/O
Y23	I/O

256-Pin FBGA			
Pin Number	A54SX16A Function	A54SX32A Function	A54SX72A Function
K5	I/O	I/O	I/O
K6	V _{CCI}	V _{CCI}	V _{CCI}
K7	GND	GND	GND
K8	GND	GND	GND
K9	GND	GND	GND
K10	GND	GND	GND
K11	V _{CCI}	V _{CCI}	V _{CCI}
K12	I/O	I/O	I/O
K13	I/O	I/O	I/O
K14	I/O	I/O	I/O
K15	NC	I/O	I/O
K16	I/O	I/O	I/O
L1	I/O	I/O	I/O
L2	I/O	I/O	I/O
L3	I/O	I/O	I/O
L4	I/O	I/O	I/O
L5	I/O	I/O	I/O
L6	I/O	I/O	I/O
L7	V _{CCI}	V _{CCI}	V _{CCI}
L8	V _{CCI}	V _{CCI}	V _{CCI}
L9	V _{CCI}	V _{CCI}	V _{CCI}
L10	V _{CCI}	V _{CCI}	V _{CCI}
L11	I/O	I/O	I/O
L12	I/O	I/O	I/O
L13	I/O	I/O	I/O
L14	I/O	I/O	I/O
L15	I/O	I/O	I/O
L16	NC	I/O	I/O
M1	I/O	I/O	I/O
M2	I/O	I/O	I/O
M3	I/O	I/O	I/O
M4	I/O	I/O	I/O
M5	I/O	I/O	I/O
M6	I/O	I/O	I/O
M7	I/O	I/O	QCLKA
M8	PRB, I/O	PRB, I/O	PRB, I/O
M9	I/O	I/O	I/O

256-Pin FBGA			
Pin Number	A54SX16A Function	A54SX32A Function	A54SX72A Function
M10	I/O	I/O	I/O
M11	I/O	I/O	I/O
M12	NC	I/O	I/O
M13	I/O	I/O	I/O
M14	NC	I/O	I/O
M15	I/O	I/O	I/O
M16	I/O	I/O	I/O
N1	I/O	I/O	I/O
N2	I/O	I/O	I/O
N3	I/O	I/O	I/O
N4	I/O	I/O	I/O
N5	I/O	I/O	I/O
N6	I/O	I/O	I/O
N7	I/O	I/O	I/O
N8	I/O	I/O	I/O
N9	I/O	I/O	I/O
N10	I/O	I/O	I/O
N11	I/O	I/O	I/O
N12	I/O	I/O	I/O
N13	I/O	I/O	I/O
N14	I/O	I/O	I/O
N15	I/O	I/O	I/O
N16	I/O	I/O	I/O
P1	I/O	I/O	I/O
P2	GND	GND	GND
P3	I/O	I/O	I/O
P4	I/O	I/O	I/O
P5	NC	I/O	I/O
P6	I/O	I/O	I/O
P7	I/O	I/O	I/O
P8	I/O	I/O	I/O
P9	I/O	I/O	I/O
P10	NC	I/O	I/O
P11	I/O	I/O	I/O
P12	I/O	I/O	I/O
P13	V _{CCA}	V _{CCA}	V _{CCA}
P14	I/O	I/O	I/O

256-Pin FBGA			
Pin Number	A54SX16A Function	A54SX32A Function	A54SX72A Function
P15	I/O	I/O	I/O
P16	I/O	I/O	I/O
R1	I/O	I/O	I/O
R2	GND	GND	GND
R3	I/O	I/O	I/O
R4	NC	I/O	I/O
R5	I/O	I/O	I/O
R6	I/O	I/O	I/O
R7	I/O	I/O	I/O
R8	I/O	I/O	I/O
R9	HCLK	HCLK	HCLK
R10	I/O	I/O	QCLKB
R11	I/O	I/O	I/O
R12	I/O	I/O	I/O
R13	I/O	I/O	I/O
R14	I/O	I/O	I/O
R15	GND	GND	GND
R16	GND	GND	GND
T1	GND	GND	GND
T2	I/O	I/O	I/O
T3	I/O	I/O	I/O
T4	NC	I/O	I/O
T5	I/O	I/O	I/O
T6	I/O	I/O	I/O
T7	I/O	I/O	I/O
T8	I/O	I/O	I/O
T9	V _{CCA}	V _{CCA}	V _{CCA}
T10	I/O	I/O	I/O
T11	I/O	I/O	I/O
T12	NC	I/O	I/O
T13	I/O	I/O	I/O
T14	I/O	I/O	I/O
T15	TDO, I/O	TDO, I/O	TDO, I/O
T16	GND	GND	GND

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
AD18	I/O	I/O
AD19	I/O	I/O
AD20	I/O	I/O
AD21	I/O	I/O
AD22	I/O	I/O
AD23	V _{CCI}	V _{CCI}
AD24	NC*	I/O
AD25	NC*	I/O
AD26	NC*	I/O
AE1	NC*	NC
AE2	I/O	I/O
AE3	NC*	I/O
AE4	NC*	I/O
AE5	NC*	I/O
AE6	NC*	I/O
AE7	I/O	I/O
AE8	I/O	I/O
AE9	I/O	I/O
AE10	I/O	I/O
AE11	NC*	I/O
AE12	I/O	I/O
AE13	I/O	I/O
AE14	I/O	I/O
AE15	NC*	I/O
AE16	NC*	I/O
AE17	I/O	I/O
AE18	I/O	I/O
AE19	I/O	I/O
AE20	I/O	I/O
AE21	NC*	I/O
AE22	NC*	I/O
AE23	NC*	I/O
AE24	NC*	I/O
AE25	NC*	NC
AE26	NC*	NC

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
AF1	NC*	NC
AF2	NC*	NC
AF3	NC	I/O
AF4	NC*	I/O
AF5	NC*	I/O
AF6	NC*	I/O
AF7	I/O	I/O
AF8	I/O	I/O
AF9	I/O	I/O
AF10	I/O	I/O
AF11	NC*	I/O
AF12	NC*	NC
AF13	HCLK	HCLK
AF14	I/O	QCLKB
AF15	NC*	I/O
AF16	NC*	I/O
AF17	I/O	I/O
AF18	I/O	I/O
AF19	I/O	I/O
AF20	NC*	I/O
AF21	NC*	I/O
AF22	NC*	I/O
AF23	NC*	I/O
AF24	NC*	I/O
AF25	NC*	NC
AF26	NC*	NC
B1	NC*	NC
B2	NC*	NC
B3	NC*	I/O
B4	NC*	I/O
B5	NC*	I/O
B6	I/O	I/O
B7	I/O	I/O
B8	I/O	I/O
B9	I/O	I/O

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
B10	I/O	I/O
B11	NC*	I/O
B12	NC*	I/O
B13	V _{CCI}	V _{CCI}
B14	CLKA	CLKA
B15	NC*	I/O
B16	NC*	I/O
B17	I/O	I/O
B18	V _{CCI}	V _{CCI}
B19	I/O	I/O
B20	I/O	I/O
B21	NC*	I/O
B22	NC*	I/O
B23	NC*	I/O
B24	NC*	I/O
B25	I/O	I/O
B26	NC*	NC
C1	NC*	I/O
C2	NC*	I/O
C3	NC*	I/O
C4	NC*	I/O
C5	I/O	I/O
C6	V _{CCI}	V _{CCI}
C7	I/O	I/O
C8	I/O	I/O
C9	V _{CCI}	V _{CCI}
C10	I/O	I/O
C11	I/O	I/O
C12	I/O	I/O
C13	PRA, I/O	PRA, I/O
C14	I/O	I/O
C15	I/O	QCLKD
C16	I/O	I/O
C17	I/O	I/O
C18	I/O	I/O

Note: *These pins must be left floating on the A54SX32A device.

Datasheet Categories

In order to provide the latest information to designers, some datasheets are published before data has been fully characterized. Datasheets are designated as "Product Brief," "Advanced," "Production," and "Datasheet Supplement." The definitions of these categories are as follows:

Product Brief

The product brief is a summarized version of a datasheet (advanced or production) containing general product information. This brief gives an overview of specific device and family information.

Advanced

This datasheet version contains initial estimated information based on simulation, other products, devices, or speed grades. This information can be used as estimates, but not for production.

Unmarked (production)

This datasheet version contains information that is considered to be final.

Datasheet Supplement

The datasheet supplement gives specific device information for a derivative family that differs from the general family datasheet. The supplement is to be used in conjunction with the datasheet to obtain more detailed information and for specifications that do not differ between the two families.

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